

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau

(43) International Publication Date
27 August 2020 (27.08.2020)



(10) International Publication Number
WO 2020/172561 A1

(51) International Patent Classification:

H01R 12/73 (2011.01) H01R 12/51 (2011.01)
H01R 43/20 (2006.01) H05K 7/02 (2006.01)
H01R 13/24 (2006.01)

(21) International Application Number:

PCT/US2020/019276

(22) International Filing Date:

21 February 2020 (21.02.2020)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

62/808,934 22 February 2019 (22.02.2019) US
16/797,536 21 February 2020 (21.02.2020) US

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(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ,
CA, CH, CL, CN, CO, CR, CU, CZ, DE, DJ, DK, DM, DO,
DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN,
HR, HU, ID, IL, IN, IR, IS, JO, JP, KE, KG, KH, KN, KP,
KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, ME,
MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ,
OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA,
SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM, TN, TR,
TT, TZ, UA, UG, US, UZ, VC, VN, WS, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, GH,
GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, ST, SZ, TZ,
UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ,

(54) Title: INTERPOSER ASSEMBLY AND METHOD

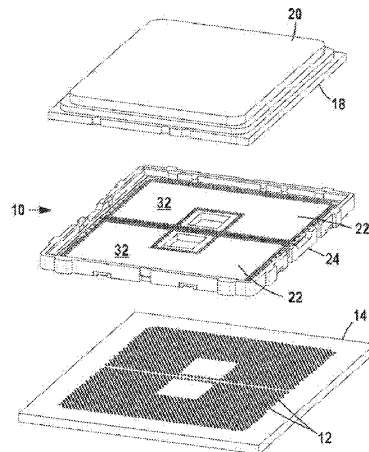


Fig. 1

(57) Abstract: An interposer assembly including a plate and a plurality of conductive contacts extending through plate passages for forming electrical connections with pads on overlying and underlying substrates. The interposer assembly includes contacts having one or more cantilever arms that form redundant contacts with a substrate pad. Each cantilever arm includes a pair of contact points for establishing reliable electrical connections with each pad.

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TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Declarations under Rule 4.17:

- *as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))*
- *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))*
- *of inventorship (Rule 4.17(iv))*

Published:

- *with international search report (Art. 21(3))*